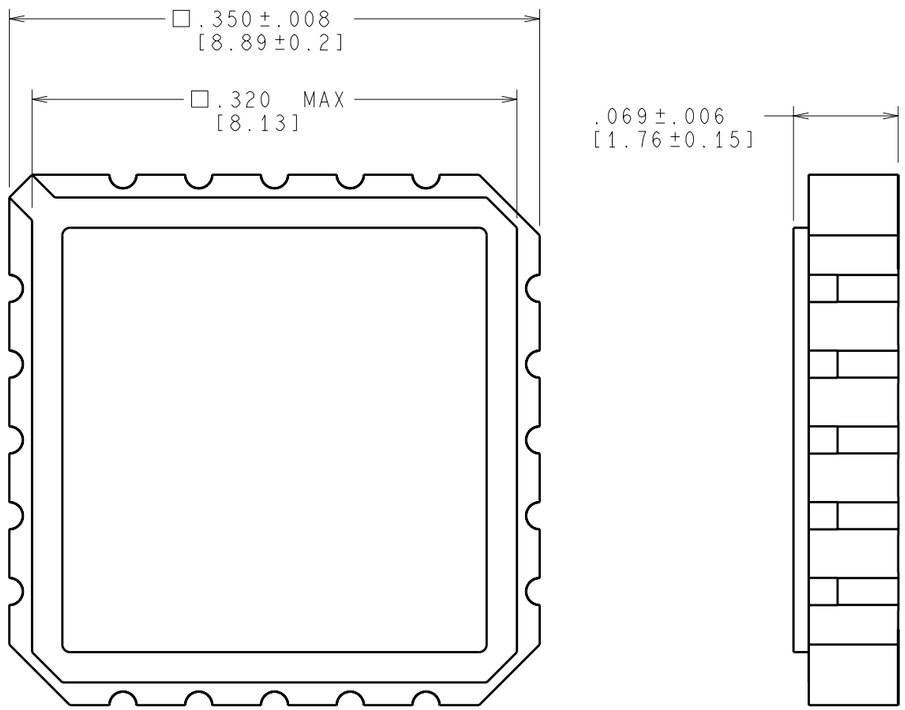
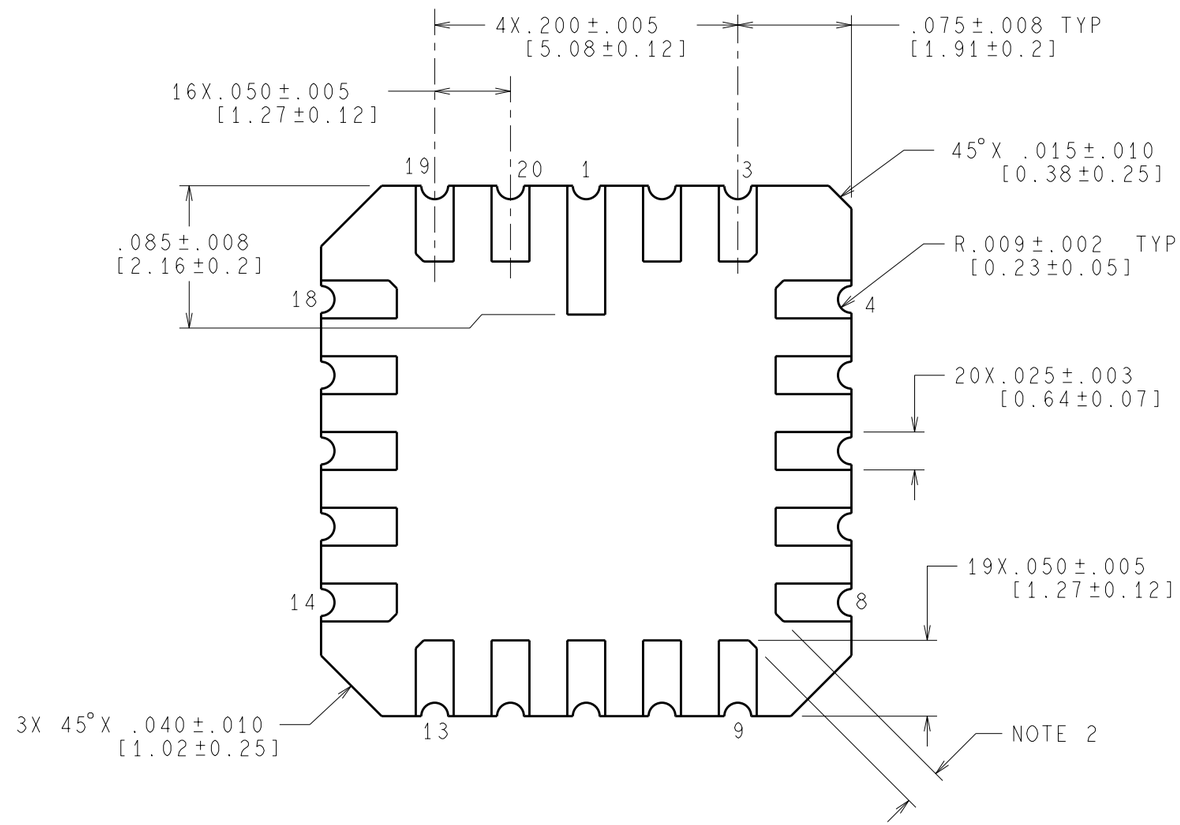
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	XREVISE AND REDRAW.	10005	02/10/1994	DEG/AP
F	REVISE NOTES 1 & 3; UPDATE MIL/AERO STAMP; CHANGE DWG FORMAT TO B SIZE.	1394	05/13/2004	MS/ACBS





CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH: SOLDER DIP.
   SOLDER THICKNESS PER LATEST REVISION OF MIL-PRF-38535.
2. CORNER PADS MAY HAVE A 45°X.020IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015IN/0.38mm DIMENSION.
3. REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB.

MIL-PRF-38535
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN *Dwayne Grady*	02/10/1994
DFTG. CHK. *THANH LEQUANG*	05/13/2004
ENGR. CHK. *ALVIN CB SIM*	05/13/2004

PROJECTION INCH (MM)

National Semiconductor
2900 Semiconductor Dr, Santa Clara, CA 95052-8090

LEADLESS CHIP CARRIER, TYPE C, 20 TERMINAL

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-E20A	F

FORMERLY: N/A

SHEET 1 of 1